



The Physics of Joining and Additive Manufacturing

Guest Editors:

Dr. Amin Ebrahimi

Dr. Marcel J.M. Hermans

Dr. Vera Popovich

Deadline for manuscript
submissions:

closed (30 September 2023)

Message from the Guest Editors

The development, control, monitoring, and optimisation of advanced joining and additive manufacturing rely on our understanding of the involved physical phenomena. Similarly, the deposition of materials to form (near) net shapes requires a deep understanding of the processes and materials in order to control shape and properties. The properties of materials depend on their composition and thermal-mechanical history. Microstructures and properties can be affected by processing. The comprehensive scope of this Special Issue includes all physical aspects of advanced joining and additive manufacturing processes of all materials. It aims at collating aspects of applied physics, engineering, materials science, and chemistry, which are crucial for the development of efficient and cost-effective joining and additive manufacturing technologies.

The categories of manuscript types that will be considered for publication include full-length original research articles, short communications, reviews, and perspectives. Manuscripts submitted to this Special Issue should contain new insights into the relationship between the processing, structure, and properties of materials.





an Open Access Journal by MDPI

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
da Vinci 32, 20133 Milano, Italy

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), Ei Compendex, Inspec, Embase, CAPlus / SciFinder, and other databases.

Journal Rank: JCR - Q2 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)

Contact Us

Applied Sciences Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/applsci
applsci@mdpi.com
[X@Applsci](https://twitter.com/Applsci)